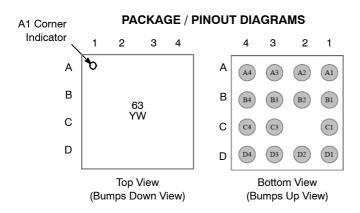
EMI Filter with ESD Protection for MicroSD Card Applications

Product Description

The EMI6316 is a 4 x 4, 15-bump EMI filter with ESD protection device for MicroSD card applications in a 0.4 mm pitch CSP form factor. It is fully compliant with IEC 61000-4-2. The EMI6316 is also RoHS II compliant.





ON Semiconductor®

http://onsemi.com

MARKING DIAGRAM



WLCSP15 CASE 567FX



63 = Specific Device Code

Y = Year

W = Work Week

= Pb-Free Package

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 3 of this data sheet.

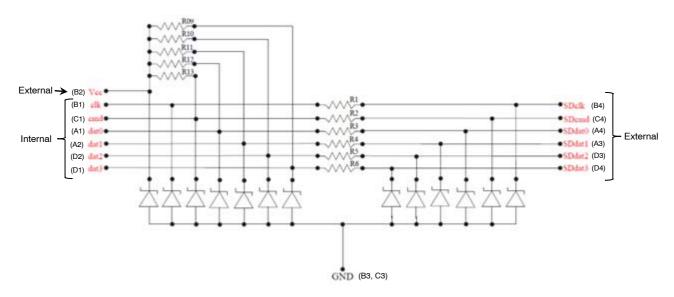


Figure 1. Electrical Schematic

Table 1. PIN DESCRIPTIONS

Pin	Description	Pin	Description	Pin	Description	Pin	Description
A1	dat0 Internal	B1	clk Internal	C1	cmd Internal	D1	data3 Internal
A2	dat1 Internal	B2	V _{CC} External			D2	data2 Internal
A3	SDdat1 External	В3	GND	C3	GND	D3	SDdata2 External
A4	SDdat0 External	B4	SDclk External	C4	SDcmd External	D4	SDdata3 External

ELECTRICAL SPECIFICATIONS AND CONDITIONS

Table 2. PARAMETERS AND OPERATING CONDITIONS

Parameter	Rating	Unit
Storage Temperature Range	-55 to +150	°C
Operating Temperature Range	-40 to +85	°C

Table 3. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R ₁ R ₂ R ₃ R ₄ R ₅ R ₆	Resistance		34	40	46	Ω
R ₉ R ₁₀ R ₁₁ R ₁₂	Resistance		42.5	50	57.5	kΩ
R ₁₃	Resistance		12.75	15	17.25	kΩ
I _{LEAK}	Leakage Current per Channel	V _{IN} = 3.0 V		10	100	nA
С	Line Capacitance	At 1 MHz, V _{IN} = 0 V	9	11.5	14	pF
		At 1 MHz, V _{IN} = 1.8 V (Note 2)		8		pF
		At 1 MHz, V _{IN} = 2.5 V		7		pF
V_{B}	Breakdown Voltage (Positive)	I _R = 1 mA	6	7	9	V
V _{ESD}	ESD Protection Peak Discharge Voltage at A3, A4, B2, B4, C4, D3 and D4 pins a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 3)	±8 ±15			kV
	ESD Protection Peak Discharge Voltage at A1, A2, B1, C1, D1 and D2 pins a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 3)	±2 ±2			

Table 4. CSP TAPE AND REEL SPECIFICATIONS†

Part Number	Chip Size (mm)	Package	Shipping [†]
EMI6316FCTBG	1.56 x 1.56 x 0.50	WLCSP15 (Pb-Free)	5000 / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

All parameters specified at T_A = 25°C unless otherwise noted.
 MicroSD version 3.0 SDR104 compliant.
 Standard IEC 61000-4-2 with C_{Discharge} = 150 pF, R_{Discharge} = 330 Ω.

RF CHARACTERISTICS

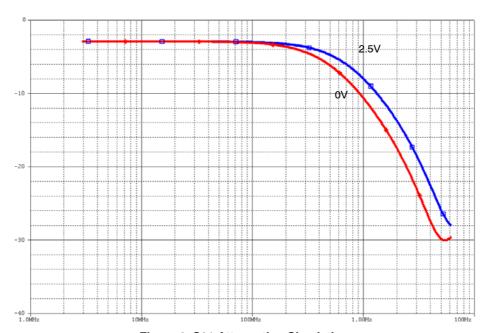
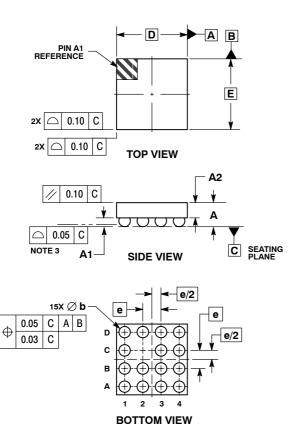


Figure 2. S21 Attenuation Simulation

PACKAGE DIMENSIONS

WLCSP15, 1.56x1.56 CASE 567FX ISSUE O

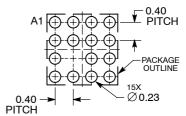


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 COPLANARITY APPLIES TO SPHERICAL
- CROWNS OF SOLDER BALLS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.47	0.53		
A1	0.185	0.205		
A2	0.305 REF			
b	0.24	0.29		
D	1.56 BSC			
E	1.56 BSC			
e	0.40 BSC			

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunit

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA **Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada

Fax: 303-675-2173 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative